

DP-310331

DUAL-SIDED SUBSTRATE INTEGRATED
CIRCUIT PACKAGE INCLUDING A LEADFRAME
HAVING LEADS WITH INCREASED THICKNESS

ABSTRACT OF THE DISCLOSURE

An integrated circuit package includes a first non-conductive substrate having a first inner surface and a second non-conductive substrate having a second inner surface. A die having a first thickness is disposed between the first and second inner surfaces. A leadframe includes a member having a proximal end and a distal end. The proximal end has a second thickness less than the first thickness. The distal end is disposed between the first and second inner surfaces. The distal end is undulated such that the distal end has an effective thickness greater than the second thickness.